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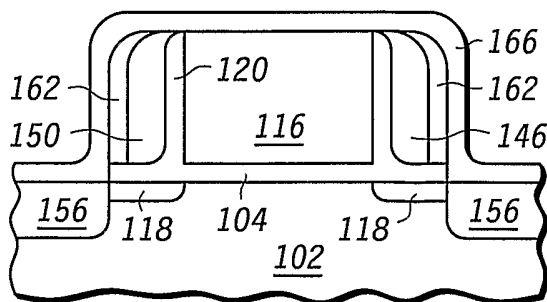
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(54) Title: SEMICONDUCTOR FABRICATION PROCESS WITH ASYMMETRICAL CONDUCTIVE SPACERS



(57) Abstract: A semiconductor process and resulting transistor includes forming conductive extension spacers (146, 150) on either side of a gate electrode (116). Conductive extensions (146, 150) and gate electrode 116 are independently doped such that each of the structures may be n-type or p-type. Source/drain regions (156) are implanted laterally disposed on either side of the spacers (146, 150). Spacers (146, 150) may be independently doped by using a first angled implant (132) to dope first extension spacer (146) and a second angled implant (140) to dope second spacer (150). In one embodiment, the use of differently doped extension spacers (146, 150) eliminates the need for threshold adjustment channel implants.

SEMICONDUCTOR FABRICATION PROCESS WITH ASYMMETRICAL CONDUCTIVE SPACERS

BACKGROUND OF THE INVENTION

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1. Field of the Invention

The present invention relates generally to the field of semiconductor fabrication and, more particularly, to a process of forming small transistors with low leakage and acceptable threshold voltages.

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2. Description of Related Art

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In the field of semiconductor devices, transistors must simultaneously exhibit high performance and low power characteristics. These two parameters typically compete with one another. As transistor channel lengths decrease, for example, to improve the speed of a device, other parameters such as the subthreshold leakage and the threshold voltage can become more difficult to control. Conventionally, doped transistor channels are employed to control threshold voltages within a desired range. These doped channels are frequently achieved using ion implantation.

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Recently, silicon on insulator (SOI) technology has been used to achieve lower power consumption. In addition, gate lengths are being scaled down with each new process technology. The shallow channels needed for SOI and deep sub-micron devices are difficult to achieve consistently with conventional channel doping implants. Without these doped channels, however, it is difficult to fabricate deep sub-micron devices that exhibit sufficiently low leakage current, adequate threshold voltages, and acceptably low threshold voltage variation. It would be desirable, therefore, to implement a process and resulting transistor having a short channel length, adequate threshold voltage, and low subthreshold leakage without significantly increasing the cost or complexity of the process.

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SUMMARY OF THE INVENTION

The problem highlighted above is addressed by a semiconductor process and resulting transistor that includes forming conductive extensions on either side of a gate

electrode. The conductive extensions and gate electrode are independently doped such that each of the structures may be n-type, p-type, or intrinsic. Source/drain regions are implanted laterally disposed on either side of the extensions. Extensions may be independently doped by using a first angled implant to dope first extension and a second angled implant to dope second extension. In one embodiment, the use of differently doped extensions eliminates the need for threshold adjustment channel implants such that the channel region of the transistor is substantially free of implanted species.

BRIEF DESCRIPTION OF THE DRAWINGS

The invention, together with further advantages thereof, may best be understood by reference to the following description taken in conjunction with the accompanying drawings in which:

FIG 1 is a partial cross-sectional view of a semiconductor wafer in which a gate dielectric is formed over a semiconductor substrate;

FIG 2 illustrates processing subsequent to FIG 1 in which a gate electrode film is formed over the gate dielectric;

FIG 3 illustrates processing subsequent to FIG 2 in which the gate electrode film is patterned to form a gate electrode structure;

FIG 4 illustrates processing subsequent to FIG 3 in which a dielectric is formed over the substrate and the gate electrode;

FIG 5 illustrates processing subsequent to FIG 4 in which a conductive film is formed over the dielectric film;

FIG 6 illustrates processing subsequent to FIG 5 in which a first portion of the conductive film is implanted with a first dopant;

FIG 7 illustrates processing subsequent to FIG 6 in which a second portion of the conductive film is implanted with a second dopant;

FIG 8 illustrates processing subsequent to FIG 7 in which the conductive film is patterned to form conductive extensions;

FIG 9 illustrates processing subsequent to FIG 8 in which a dielectric film is formed over the extensions and the gate electrode;

FIG 10 illustrates processing subsequent to FIG 9 in which the dielectric film is etched to form dielectric spacers;

5 FIG 11 illustrates processing subsequent to FIG 10 in which source/drain regions of the substrate are implanted using the gate electrode, the extensions, and the dielectrics as an implant mask;

FIG 12 illustrates processing subsequent to FIG 11 in which a metal film is deposited over the wafer;

10 FIG 13 illustrates processing subsequent to FIG 12 in which the gate electrode and the extensions are tied together by a heat treatment of the silicide; and

FIG 14 is a top view of an alternative method of connecting the extensions to the rest of the transistor.

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DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

Reference will now be made in detail to the presently preferred embodiments of the invention, examples of which are illustrated in the accompanying drawings. It should be noted that the drawings are in simplified form and are not to precise scale. Although the invention herein refers to certain illustrated embodiments, it is to be understood that these embodiments are presented by way of example and not by way of limitation. The intent of the following detailed description is to cover all modifications, alternatives, and equivalents as may fall within the spirit and scope of the invention as defined by the appended claims.

It is to be understood and appreciated that the process steps and structures described herein do not cover a complete process flow for the manufacture of an integrated circuit. The present invention may be practiced in conjunction with various integrated circuit fabrication techniques that are conventionally used in the art, and only so much of the commonly practiced process steps are included herein as are necessary to provide an understanding of the present invention.

Generally speaking, the present invention contemplates the formation of a transistor that employs electrically conductive, spacer structures (referred to herein as extensions) on the sidewalls of the transistor gate electrode. Together with the conventional gate electrode structure, the conductive spacers form a three-part transistor gate. The polarity of each of the three gate structures is individually controllable such that the transistor may have, for example, two structures of one polarity and one structure of another. The ability to provide, in this manner, asymmetrically doped extensions, beneficially improves the ability to control the threshold voltage, subthreshold leakage and channel length of very short channel transistors.

Referring now to FIG 1, a gate dielectric film **104** is formed over a semiconductor substrate **102** of a semiconductor wafer **100**. In one embodiment, gate dielectric **104** is a silicon dioxide film formed by the thermal oxidation of the upper surface of semiconductor substrate **102**. Thermal oxidation of substrate **102** is achieved by exposing the wafer to an oxidizing ambient (*e.g.*, O₂, H₂O) at a temperature in excess of 900 °C as will be well known to those in the field of semiconductor fabrication processes. In this embodiment, gate dielectric **102** has a thickness of anywhere from 15 to 150 angstroms. In other embodiments, gate dielectric **104** is a "high K" dielectric having a dielectric

constant greater than 4.0. High K dielectrics are desirable for use in gate dielectric films to achieve sufficient capacitance with a thicker film. Materials suitable for use in a high K embodiment of dielectric **104** include various metal-oxide compounds such as hafnium-oxide as well as other materials including aluminum oxide, hafnium silicate, zirconium-silicate, hafnium aluminate, lanthanum aluminate, zirconium aluminate, and lanthanum oxide. Additional information regarding high K dielectrics is found in, for example, Samavedam, *Transistor having a high K dielectric and short gate length and method therefor*, US Patent 6,514,808.

An upper portion of semiconductor substrate **102** typically includes a monocrystalline semiconductor material such as silicon on which gate dielectric **104** is formed. In one embodiment particularly suitable for use with low power applications such as mobile and wireless devices, semiconductor substrate **102** is a silicon-on-insulator (SOI) substrate in which the monocrystalline silicon is a relatively thin film (i.e., less than 10,000 angstroms) formed over a buried oxide with a thickness roughly in the range of 1000 to 20,000 angstroms.

Referring now to FIG 2, a gate electrode film **106** is formed over gate dielectric **104**. In one embodiment, gate electrode film **106** is a polysilicon film formed by thermally decomposing silane in a reactor chamber maintained at a temperature in the range of approximately 550-650 °C. The polysilicon film is likely deposited as undoped silicon and subsequently doped with an n-type (e.g., phosphorous, arsenic) or p-type (e.g., boron) dopant using ion implantation. In other embodiments, the polysilicon may be doped in-situ or by diffusion. In still other embodiments, gate electrode film may comprise a material or compound including, in addition to or in lieu of polysilicon, germanium, tantalum silicon nitride, titanium nitride, molybdenum nitride or a combination thereof.

Referring now to FIG 3, gate electrode film **106** is patterned to form a gate electrode **116** having substantially vertical sidewalls **112**. Patterning of gate electrode **116** is achieved using photolithography processing and anisotropic or dry etch techniques that are well known in the field. The photolithography processing may include the use of an anti-reflective coating (ARC) and photoresist patterning techniques.

Referring now to FIG 4, an extension dielectric film **120** is formed over gate electrode **116**. In one embodiment, dielectric film **120** is a low-K dielectric having a

dielectric constant of less than approximately 4.0. In other embodiments, dielectric film **120** includes a film of chemically vapor deposited (CVD) silicon nitride. In this embodiment, the CVD silicon nitride is likely formed by reacting dichlorosilane or silane and ammonia in a reactor maintained at a temperature in the range of 300 to 800 °C. A CVD silicon oxide pad layer may be deposited over gate electrode **116** prior to depositing the silicon nitride to alleviate stress that occurs when silicon nitride contacts silicon. The CVD dielectric film **120** is deposited in a substantially conformal manner such that the film thickness in vertical portions of the topography is roughly within at least 80% of the film thickness in horizontal portions of the topography.

Dielectric film **120** may be anisotropically etched or left as deposited. If dielectric film **120** is etched, the portions of the film adjacent the sidewalls of gate electrode **116** remain to provide isolation between gate electrode **116** and a subsequently deposited conductive extension structure. It is also desirable to leave a dielectric film over the portions of substrate **102** not covered by gate electrode **116** to isolate the conductive extension structure from substrate **102**. If film **120** is etched, isolation from the substrate may be provided by the portions of gate dielectric **104** that remain after film **120** is etched. In addition, if film **120** includes silicon nitride over a silicon oxide pad layer, the etch of film **120** preferably removes the silicon nitride while leaving behind the silicon oxide.

One or more implant steps may be performed after forming dielectric film **120**. In one embodiment, one or more extension implants are performed to introduce source drain extension regions **118** into those portions of substrate **102** not covered by gate electrode **116**. The source/drain extension regions will be referred to as LDD regions **118** to avoid confusion with the conductive extension mentioned above and further described below. The LDD implant regions **118** are desirable to control the threshold voltage and effective channel-length of the resulting device. In an SOI embodiment of substrate **102**, however, high dose ion implantation is undesirable because it is difficult to maintain the dose adequately within the very shallow silicon substrate. To address this problem, the LDD implants may be eliminated entirely from certain embodiments of the process in which case threshold voltage control is achieved by varying the doping polarity of one of the extensions (as described in more detail below).

Referring now to FIG 5, an electrically conductive extension spacer film **124** is deposited over dielectric film **120**. In one embodiment, extension spacer film **124** is a

CVD polysilicon formed in substantially the same manner as the polysilicon embodiment of gate electrode film **106** (see description of FIG 2). In this embodiment, the polysilicon is deposited as an undoped film so that various portions of the film may subsequently be doped as desired. In other embodiments, extension spacer film **124** is an alternative
5 conductive film such as silicon germanium or a tantalum or titanium based metal.

Referring now to FIG 6 and FIG 7, first and second implants **132** and **140** are performed. First implant **132** is performed at a first implant angle typically between 6° to 60° to introduce a first dopant into conductive extension film **124**. The implant angle used during first implant **132** causes the implant species to reside primarily in a portion **136** of
10 conductive extension **124** “exposed” by the implant angle. By using an appropriate implant angle and orienting the transistors appropriately on wafer **100** (with respect to the wafer flat, for example), first implant **132** produces a first doping profile in first portion **136** of conductive extension film **124** where first portion **136** of extension film **124** represents the portion of film **124** on a first sidewall **112** of gate electrode **116**.

15 Similarly, second implant **140** introduces a second doping profile primarily into a second portion **142** of extension film **124** by using a second implant angle. The second implant angle is likely the opposite of the first implant angle used during first implant **132**. If, for example, the angle of first implant **132** is 10°, the angle of second implant **140** is likely -10°. In an embodiment suitable for controlling the threshold voltage and
20 subthreshold leakage of the transistor, the polarities of the implant species used during first implant **132** and second implant **140** are opposite. Thus, first implant **132** may use a p-type species such as boron while second implant **140** uses an n-type species such as phosphorous or arsenic. In one particular embodiment suitable for fabricating n-channel transistors, for example, conductive gate **116** and second portion **142** of extension film **124**
25 are n-doped while first portion **136** of extension film **124** is p-doped. In this embodiment, when the region under first portion **136** of film **124** is the used as the device’s drain region, the resulting transistor will have an improved (elevated) V_t and a lower subthreshold leakage than a corresponding transistor in which the entire gate structure is doped with a uniform polarity.

30 The implant dosage of first and second implants **132** and **140** should be sufficient to achieve a highly doped first and second portion **136** and **142** of extension film **124** respectively. In an embodiment, in which first implant **132** is a p-type implant and second

implant **140** is an n-type implant, a desirable dose for the implant is in excess of approximately 10^{13} ions/cm². The implant energy is desirably sufficient to achieve peak dose near the center of extension film **124**. A representative implant energy for p-type (Boron) implants is in the range of approximately 10 to 100 keV while n-type (phosphorous) implants are in the range of approximately 30 to 100 keV. In other embodiments, additional or alternative implant techniques, such as plasma implantation and blocking layers (to fine tune an existing implant) may be used.

Turning now to FIG 8, conductive extension film **124** of FIG 7 has been anisotropically etched to produce first and second conductive extension spacer structures **146** and **150** respectively. As shown in FIG 8, conductive extension spacers **146** and **150** are electrically isolated from gate electrode **116** and substrate **102** by dielectrics **120** and **104**. In one embodiment, the lateral thickness of extension spacers **146** and **150** is approximately 1/4 to 1/2 the lateral dimension (the L) of gate electrode **116**. If, for example, gate electrode **116** is an L of approximately 100 nm, the lateral thickness of extension spacers **146** and **150** is in the range of approximately 25 to 50 nm together or individually. In other embodiments, the lateral dimensions of extension spacers **146** and **150** may be outside of this range.

Referring now to FIG 9 and FIG 10, a dielectric spacer film **158** is deposited and etched to form dielectric spacers **162** on the exterior sidewalls of extension spacers **146** and **150**. Spacer film **158** may be a CVD silicon oxide, silicon nitride, or a combination of the two. Spacers structures **162** beneficially prevent shorting between source/drain regions and the gate electrode of the resulting transistor. More specifically, one embodiment of the process employs a silicide sequence to short extension spacers **146** and **150** to gate electrode **116**. In this embodiment, spacer structures **162** prevent the silicide from shorting the source/drain regions to the extensions.

Referring now to FIG 11, a source/drain implant **154** is performed to introduce a source/drain impurity distribution (region) **156** into substrate **102** using gate electrode **116**, extensions spacers **146** and **150**, and dielectric spacers **162** as an implant mask such that the source/drain regions **156** are self-aligned to spacers **162** and, because spacers **162** are preferably relatively thin and uniform, source/drain regions **156** are effectively self-aligned to extensions spacers **146** and **150**. In another embodiment, implant **154** is performed prior to forming dielectric spacers **162** such that source/drain regions **156** are

directly self-aligned to extensions spacers **146** and **150**. In either embodiment, source/drain regions **156** are aligned to extension spacers **146** and **150**. In an n-channel transistor embodiment, source/drain implant uses an n-type species such as phosphorous or arsenic while in a p-channel transistor embodiment, source/drain implant **154** uses boron or another p-type dopant. The impurity distribution **156** is preferably in excess of roughly 10^{19} atoms/cm³.

Referring now to FIG 12 and FIG 13, the extension spacers **146** and **150** are electrically connected to gate electrode **116** using a silicide process. In FIG 12, a metal **166** such as cobalt is uniformly deposited over wafer **100**. Prior to this deposition, the dielectric(s), including dielectric film **120**, over source/drain regions **156** and any residual dielectric on an upper surface of gate electrode **116** are cleared to expose the doped semiconductor within substrate **102** and the polysilicon or other material of gate electrode **116**. To the extent that the dielectrics to be cleared include silicon-oxide, an HF dip or other suitable wet process may be employed while silicon nitride and other dielectrics may require conventional dry etch processing.

After metal **166** is deposited, wafer **100** and metal **166** are exposed to a heated ambient **170** to form silicide wherever metal **166** contacts silicon (or other semiconductor). The portions of metal **166** in contact with a dielectric, such as spacers **162**, remain unreacted after the heat step thereby enabling the unreacted portions to be selectively removed as shown in FIG 13. This silicide process produces a conductive bridge **174** that electrically connects first and second extension spacers **146** and **150** to gate electrode **116**. In addition to or in lieu of cobalt, metal **166** may include a material such as nickel, titanium, titanium nitride and combinations thereof.

The resulting transistor **110** as shown in FIG 13 includes a three part biasing structure that includes gate electrode **116**, and first and second conductive extension spacers **146** and **150**, each of which is situated above and is isolated from an underlying substrate **102** by an intervening dielectric. Dielectric **120** intervenes between extension spacers **146** and **150** and the sidewalls of gate electrode **116**. Source/drain regions **156** within the substrate reside on either side of a channel region **111** defined by the extension spacers **146** and **150**. Voltages applied to the extension spacers **146** and **150**, as well as gate electrode **116**, modulate the conductivity of the channel region **111**.

In the preferred embodiment, the polarities or doping types of the components of the biasing structure are independently variable. Thus, each of the three components of the biasing structures may be n-type or p-type or intrinsic. Because of work functions differences associated with different conductivity types, a common voltage applied to each of the three parts of the gate structure can have a different modulating effect on the underlying channel **111**.

In one embodiment, the region **156** under first extension spacer **146** is used as the transistor's drain. In this embodiment, first extension spacer **146** is doped p-type while gate electrode **116** and second extension spacer **150** are both doped n-type. This configuration beneficially produces an energy band gap peak near the drain that effectively raises the transistor's threshold voltage and reduces short channel effects including the subthreshold leakage and DIBL (drain induced barrier leakage).

Referring now to FIG 14, an alternative means for contacting and biasing extension spacers **146** and **150** is depicted. Instead of bridging extension spacers **146** and **150** to gate electrode **116** using a silicide process as described above with respect to FIG 12 and FIG 13, contacts **180** and **184** are used to tie extension spacers **146** and **150**, respectively, to p+ and n+ portions of substrate **102** respectively. In this embodiment, a non-critical mask and etch sequence is used to form voids **186** that "split" the extension structure into two electrically isolated portions. This embodiment enables independent biasing of the components of the transistor's biasing structure, which may be beneficial in controlling threshold voltages in particular applications.

Thus it will be apparent to those skilled in the art having the benefit of this disclosure that there has been provided, in accordance with the invention, a process for fabricating an integrated circuit that achieves the advantages set forth above. Although the invention has been described and illustrated with reference to specific illustrative embodiments thereof, it is not intended that the invention be limited to those illustrative embodiments. Those skilled in the art will recognize that variations and modifications can be made without departing from the spirit of the invention. It is therefore intended to include within the invention all such variations and modifications as fall within the scope of the appended claims and equivalents thereof.

WHAT IS CLAIMED IS:

1. A method of forming a transistor, comprising:
 - forming a gate electrode over a gate dielectric over a semiconductor substrate;
 - 5 forming electrically conductive first and second extension spacers adjacent respective first and second sidewalls of the gate electrode with a dielectric intermediate between each of the extension spacers and its respective gate electrode sidewall;
 - 10 doping the first extension spacer with a first species and the second extension spacer with a second species, wherein the polarities of the first and second extensions spacers are opposite; and
 - 15 forming source/drain regions in the substrate aligned to the extension spacers.
2. The method of claim 1, further comprising electrically bridging the gate electrode to the first and second conductive extensions with a silicide.
- 20 3. The method of claim 1, further comprising electrically contacting the first extension spacer to a first portion of the substrate and the second extension spacer to a second portion of the substrate therein enabling independent biasing of the first and second extension spacers.
- 25 4. The method of claim 1, further comprising forming an extension implant region self-aligned to the gate electrode prior to forming the extension spacers.
5. The method of claim 1, wherein doping the first extension spacer comprises ion implanting a first dopant while maintaining the substrate at an implant angle in the range
30 of 6° to 60° and wherein doping the second extension spacer comprises ion implanting a second dopant while maintaining the substrate at an implant angle in the range of -6° to -60° .

6. The method of claim 1, wherein forming the extension spacers comprises depositing an electrically conductive extension spacer film over the substrate and gate electrode and anisotropically etching the extension spacer film.

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7. The method of claim 6, wherein doping the first extension spacer and the second extension spacer is performed after depositing the extension space film and prior to etching the film.

10 8. The method of claim 6, wherein doping the first extension spacer and the second extension spacer is performed after etching the extension spacer film.

9. The method of claim 1, wherein forming the gate electrode is further characterized as:

15 forming an n-type gate electrode;

forming the first extension spacer is further characterized as forming an n-type extension spacer; and

20 forming the second extension spacer is further characterized as forming a p-type extension spacer.

10. A transistor in an integrated circuit, comprising:

25 a gate electrode over a gate dielectric over a substrate;

first and second electrically conductive extension spacers adjacent respective sidewalls of a the gate electrode with an extension dielectric intermediate between each extension spacer and its respective gate electrode sidewall, wherein at least one of said gate electrode, first extension spacer, and second extension spacer has a first conductivity type and at least one has a second conductivity type; and

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source/drain impurity regions in the substrate aligned to the extension spacers to define a channel region under the gate electrode and the first and second extension spacers.

5 11. The transistor of claim 10, wherein the first extension spacer and the gate electrode have a first conductivity type and the second electrode has a second conductivity type that differs from the first conductivity type.

12. The transistor of claim 11, wherein the first extension spacer and the gate electrode are
10 n-type, the second extension spacer is p-type, and the source/drain regions are n-type.

13. The transistor of claim 12, wherein the source/drain region proximal to the second extension spacer is further characterized as the drain region.

15 14. The transistor of claim 10, further comprising a conductive silicide bridging the first extension gate, the gate electrode, and the second electrode.

15. The transistor of claim 10, wherein the first extension spacer electrically contacts an n+ portion of the substrate and the second extension spacer contacts a p+ portion of the
20 substrate therein enabling independent biasing of the first and second extension spacers.

16. A semiconductor fabrication method, comprising:

forming first and second electrically conductive extension spacers adjacent
25 respective sidewalls of a gate electrode formed over a semiconductor substrate, the gate electrode having a first type of conductivity;

doping the first electrically conductive spacer with an impurity of the first conductivity type and the second electrically conductive spacer with an impurity of
30 a second conductivity type;

forming source/drain regions in the substrate laterally aligned to the first and second extension spacers, the source/drain regions defining a channel region between them wherein the channel region is modulated by a voltage applied to the gate electrode, the first extension spacer, or the second extension spacer.

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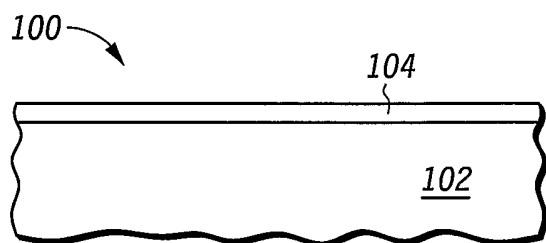
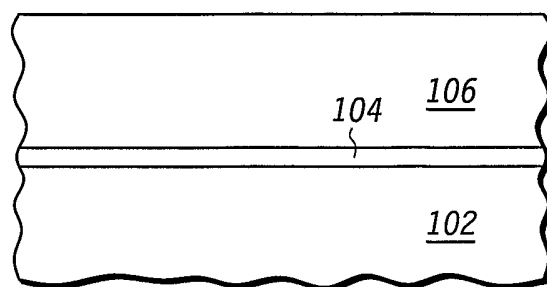
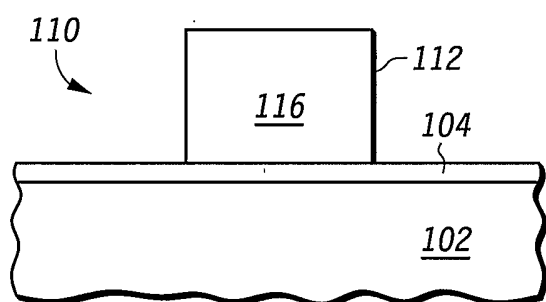
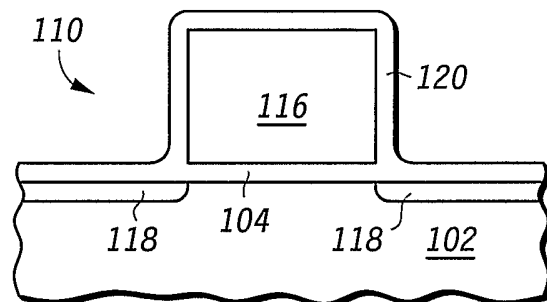
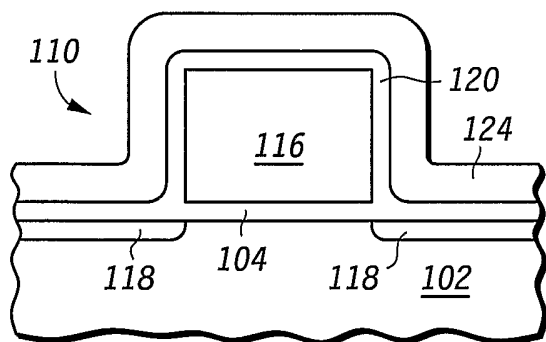
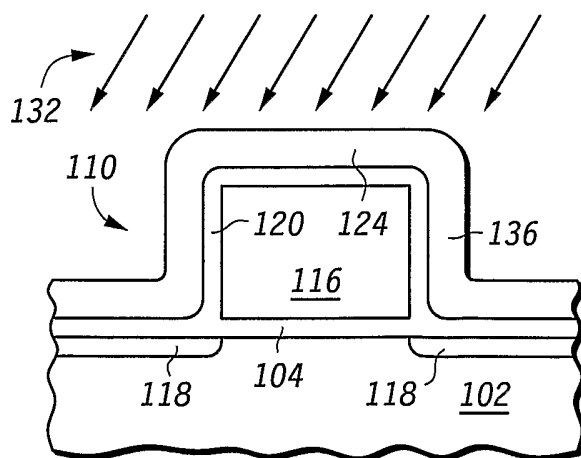
17. The method of claim 16, wherein the gate electrode, first extension spacer, and second extension spacer comprise polysilicon.

18. The method of claim 16, wherein doping the first extension spacer comprises
10 implanting an extension spacer film with a first implant performed using a first implant angle and wherein doping the second extension spacer comprises implanting the extension spacer film with a second implant performed using a second implant angle.

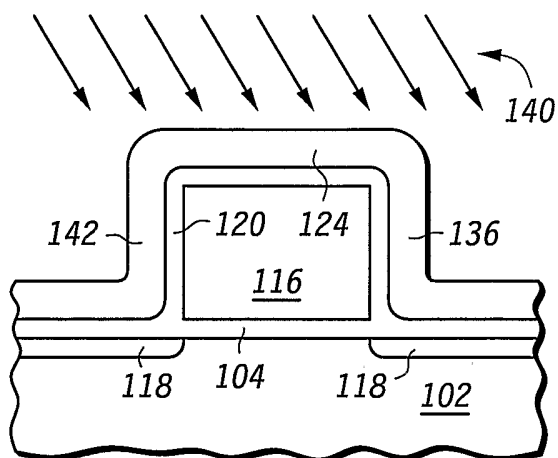
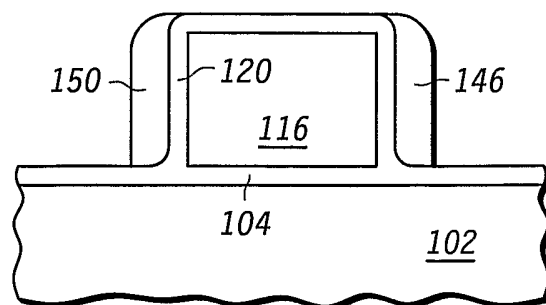
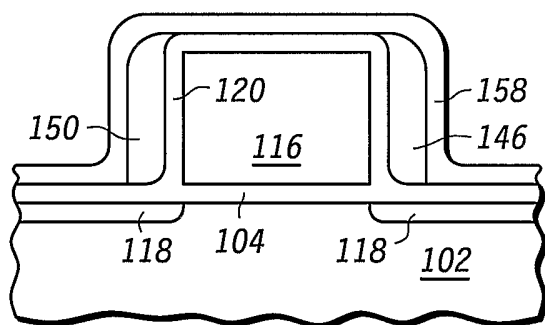
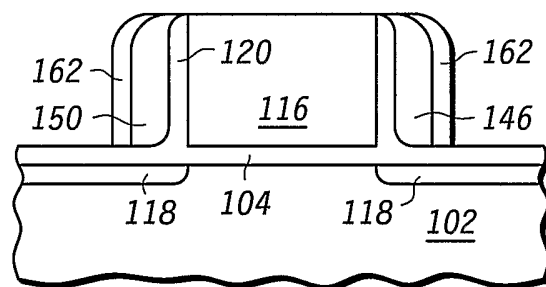
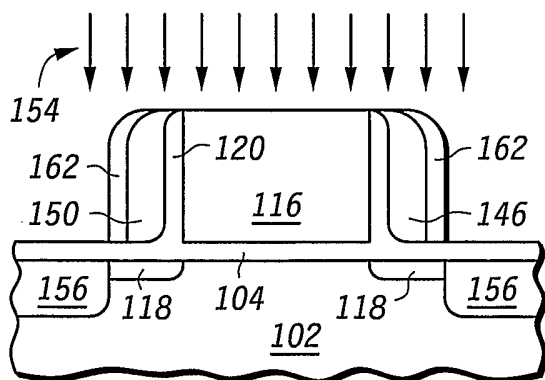
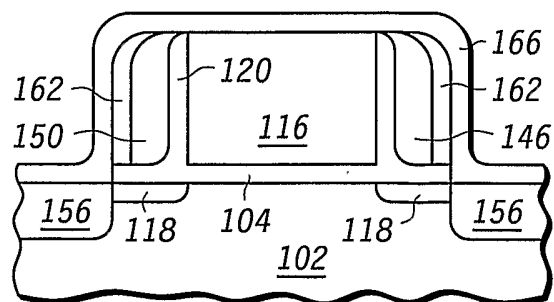
19. The method of claim 16, further comprising bridging the first extension spacer, the
15 gate electrode, and the second extension spacer with a conductive silicide.

20. The method of claim 16, further comprising, electrically connecting the first extension spacer to a first portion of the substrate and the second extension spacer to a second portion of the substrate therein enabling independent biasing of the extension spacers.

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*FIG. 1**FIG. 2**FIG. 3**FIG. 4**FIG. 5**FIG. 6*

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**FIG. 7****FIG. 8****FIG. 9****FIG. 10****FIG. 11****FIG. 12**

